- 散熱原理 Heat Dissipation Principle -

特點：具有較大的貼合接觸面積，有助於降低整體系統的熱阻。

結構：內壁具有毛細結構的真空腔體，通常採用銅製造。

原理：1) 熱傳導至蒸發區時，腔體內的冷卻液受熱產生蒸發，使氣態的工作流體充滿整個腔體。

2) 氣態工作流體接觸到冷凝區時，產生凝結現象，釋放出在蒸發時累積的熱。

3) 液態工作流體通過毛細作用回到蒸發熱源處，實現迴圈導熱的效果。

Characteristics: Larger contact area reduces overall thermal resistance.

Structure: Vacuum chamber with capillary structures, typically copper.

Working Principle: Heat conducts to evaporation region, leading to coolant evaporation, gas filling, condensation, and liquid return via capillary action.

- 技術基礎 Technical Foundation -

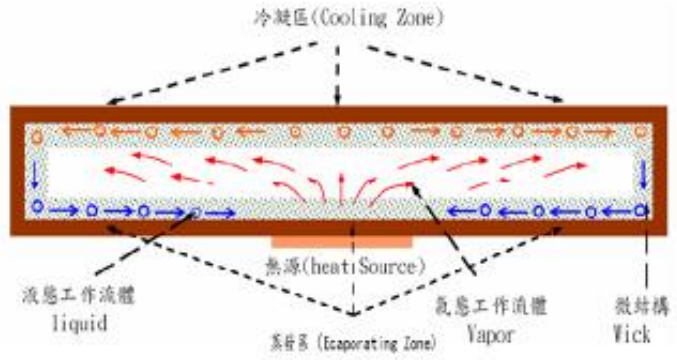
源自熱管技術的衍生產品，設計基於二維熱傳遞系統，具有高效的熱傳遞性能和溫度均溫效果。

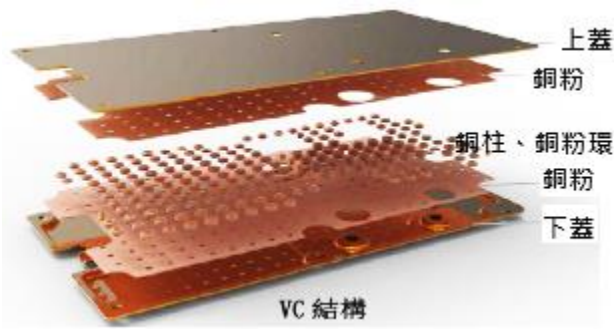
Derived from heat pipe technology, designed based on a two-dimensional heat transfer system, featuring high thermal conductivity and temperature uniformity.

- 應用範圍 Application Range -

電腦、筆記型電腦、機上盒、智慧手機等空間受限的電子產品中廣泛應用。

Widely used in space-constrained electronic products such as computers, laptops, set-top boxes, and smartphones.





如有尺寸規格需求，請洽艾美業務單位。
If there are size specifications required, please contact the sales department of I.M TECH

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以上技術資料為檢驗的平均數據。請根據您的實際使用情況選擇適合的產品，最終決定應基於您的試用結果。
The above technical data represents the average results obtained from inspections. Please choose products based on your actual usage conditions. The final decision should rely on your trial results.